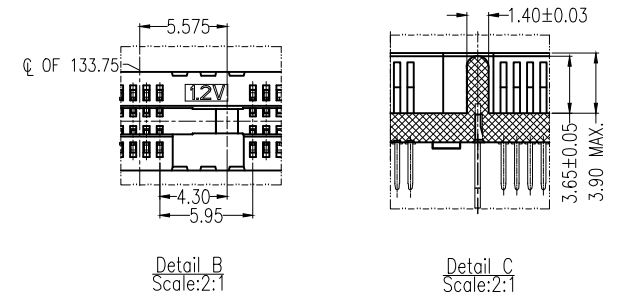
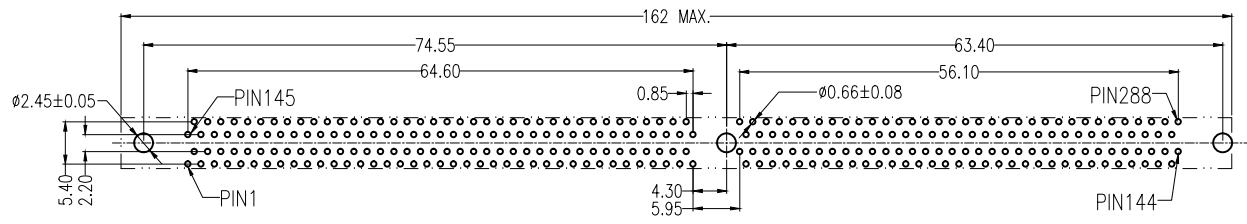
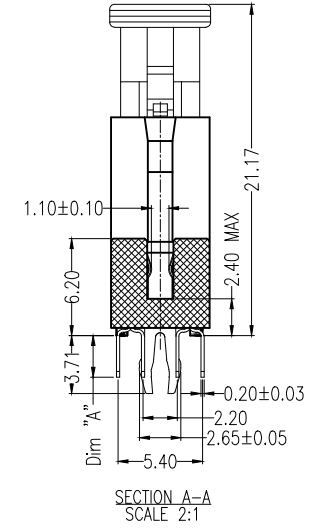
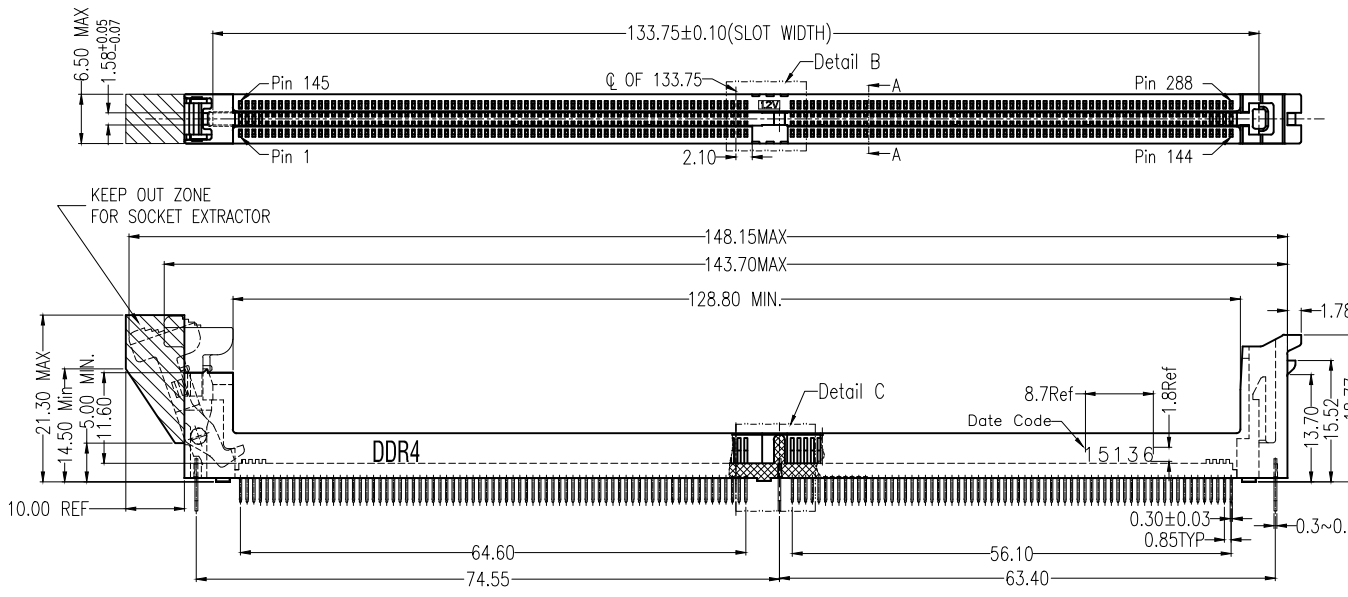


PROPRIETARY INFORMATION
COMPANY CONFIDENTIAL

REV.	ECN. NO.	DESCRIPTION	ENG	DATE
A		INITIAL	Lucky	09/14/16



DATE	DESCRIPTION
15 13 6	Saturday 13 Weeks Year

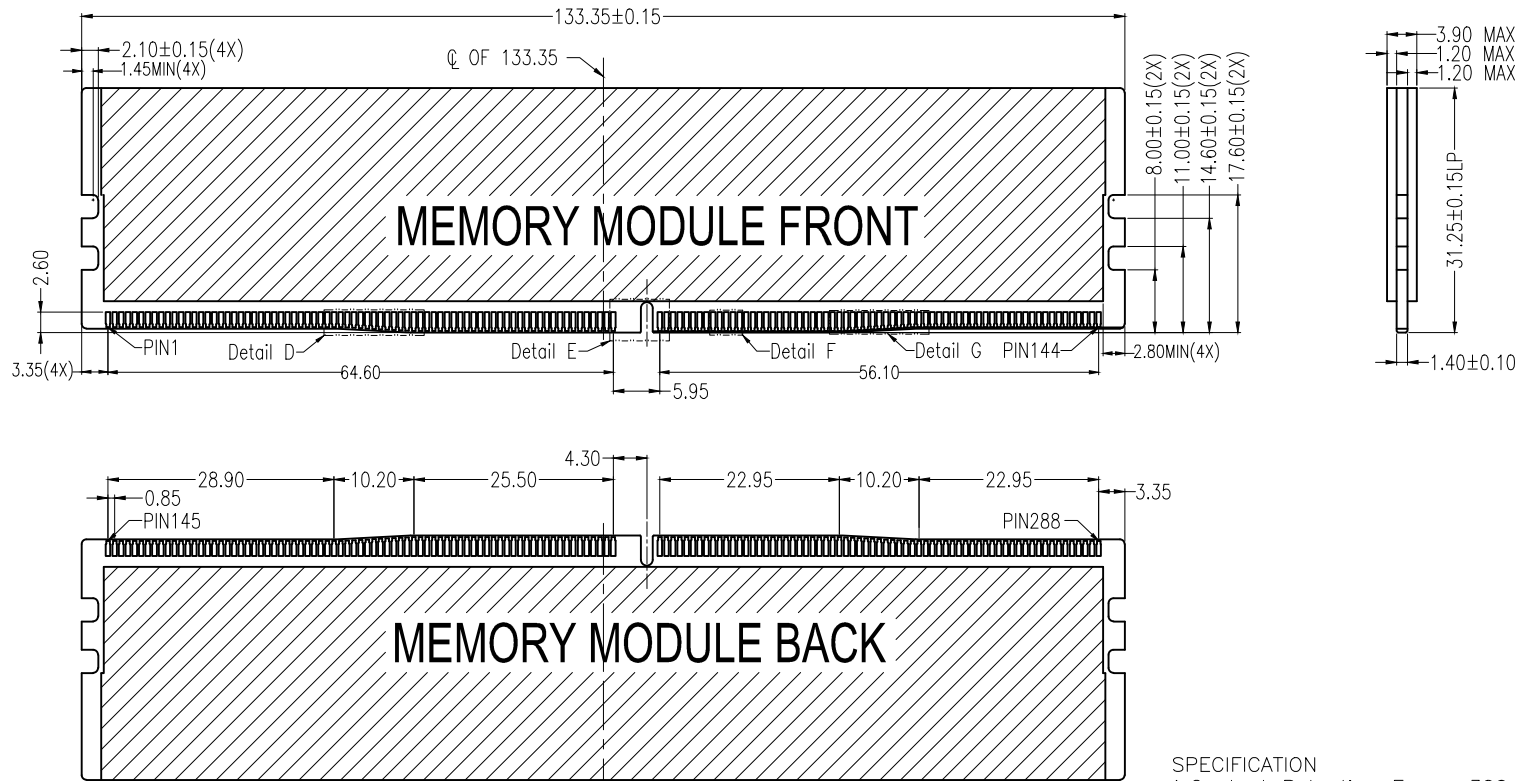
GENERAL TOLERANCE	ANGLE TOLERANCE	DRAWN	DATE	
.X± 0.35 .XX± 0.25 .XXX± 0.15	±3'	Lucky	09/14/16'	
MATL	SEE BOM	CHECKED	DATE	TITLE: DDR4-288P 0.85mm Pitch Short Slot Single Ejector DIP Type
FINISH	SEE NOTES	APPROVED	DATE	PART NUMBER: 105-10008-01
SCALE	N/A			DRAWING NO. 105-10008
SHEET	1 OF 2			SIZE A4 REV. A

ITEM	NAME	Q'TY	DESCRIPTION	NOTE
2	CANTACT	288	BRASS NICKEL(40u" MIN.) UNDER PLATING OVERALL,TIN(100U"MIN.) PLATING ON SOLDER AREA; GOLD FLASH PLATING ON CONTACT AREA	
1	HOUSING	1	PA66 BLACK	UL94V-0

PROPRIETARY INFORMATION
COMPANY CONFIDENTIAL

REV.	ECN. NO.	DESCRIPTION	ENG	DATE
A		INITIAL	Lucky	09/09/16

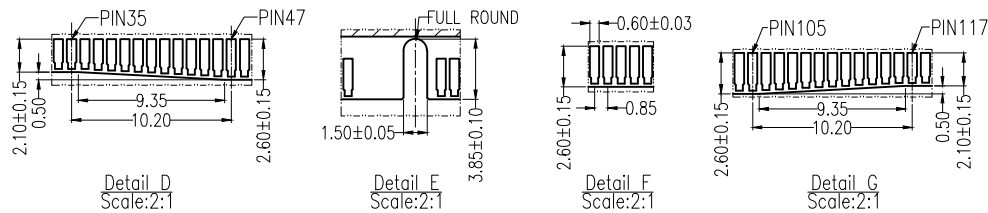
A
B
C
D
E



Recommended Memory Module Layout

SPECIFICATION

- Contact Retention Force: 300 Grams Min. Per Pin;
- Insertion Force: 10.88Kgf Max. With Module Thickness 1.50mm;
- Unmating Force: 14gf Min. Per Pin Pair With Module Thickness 1.30mm;
- Durability: 25 cycles;
- Contact Resistance: 10mΩ Max. Initial ,Change Value to 20mΩ Max;
- Insulation Resistance: Apply 500V DC 1MΩ Min. ;
- Withstand Voltage: 500V AC.
- Solderability: Compliance with EIA-364-52,Class 2,Catgory 3;
- Vibration: Compliance with EIA-364-28;
- Humidity: Compliance with EIA-364-21;
- Thermal shock: Compliance with EIA-364-32;
- Operating Temperature: -55°C TO +85°C;
- Mechanical shock: Compliance with EIA-364-27.



GENERAL TOLERANCE .X± 0.35 .XX± 0.25 .XXX± 0.15	ANGLE TOLERANCE ±3°	DRAWN Lucky	DATE 09/14/16'		TITLE DDR4-288P 0.85mm Pitch Short Slot Single Ejector DIP Type
MATL SEE BOM	FINISH SEE NOTES	CHECKED	DATE		PART NUMBER 105-10008-01
SCALE N/A	UNIT mm	APPROVED	DATE	DRAWING NO. 105-10008	SIZE A4
SHEET 2 OF 2					REV. A